

# Simulating Monolithic Active Pixel Sensors Using Generic Doping Profiles

Adriana Simancas on behalf of the Tangerine Project  
+ D. Dannheim, K. Dort, W. Snoeys  
4<sup>th</sup> Allpix Squared Workshop  
23 May 2023  
Hamburg, Germany



# Introduction & Motivation

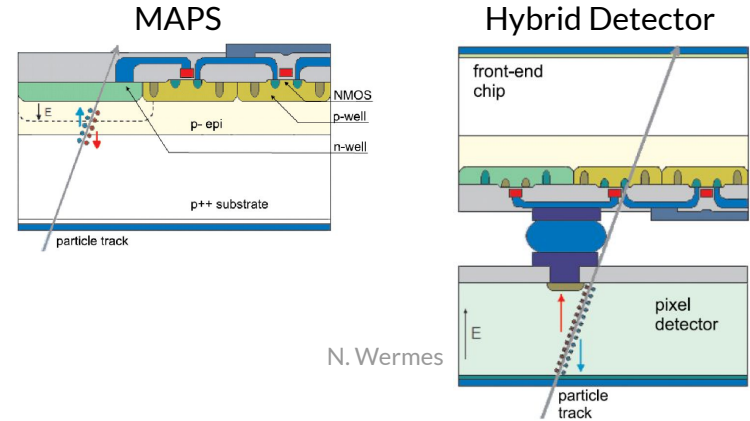
Monolithic active pixel sensors (MAPS) in particle physics:

- ★ Reduction in material budget compared to most hybrid detectors

Science moving to CMOS commercial foundries

Advantages & Disadvantages:

- ★ Solution to single-vendor problem
- ★ Profit from state-of-the-art technology
- ★ Reduce costs in large-scale production
- ★ Limited access to manufacturing process information

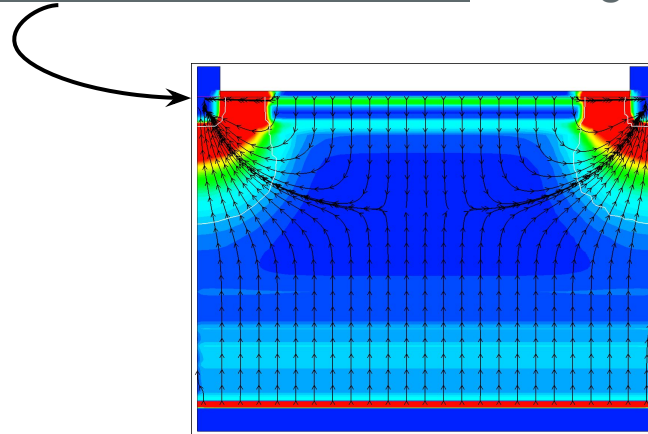


N. Wermes


# Introduction & Motivation

Developing a new detector:

- ★ Prototype Testing: characterize sensor under realistic conditions
- ★ **Simulations:** predict sensor behaviour and test designs
  - Electric field distribution in sensor highly dependent on doping concentration and doping profiles
  - MAPS with a small collection electrode have highly complex electric fields



# A Technology-Independent Approach Using Generic Doping Profiles

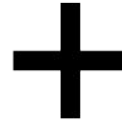
- ★ Performing simulations based on **fundamental principles** of silicon detectors and using **generic doping profiles**
  - MAPS performance parameters can be inferred
- ★ **Do not** aim to resolve CMOS imaging processes, but merely describe general features relevant for sensor volume response
- ★ Results shown in context of **Tangerine Project** (see following talks) 
- ★ Methodology described is useful for many different silicon sensor simulations
  - Toolbox for similar simulations
    - Extracting reasonable description of sensor behaviour

# Tools

**Sentaurus  
TCAD**

**SYNOPSYS**<sup>®</sup>  
*Silicon to Software*<sup>™</sup>

Technology Computer-Aided Design

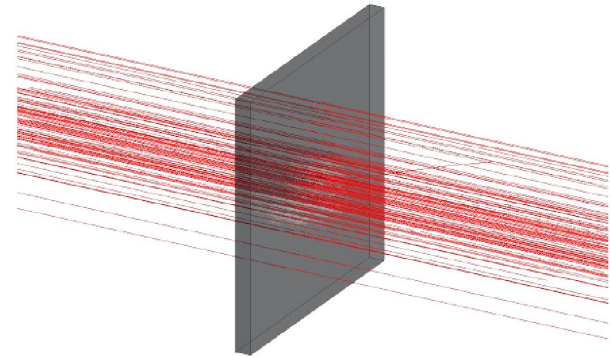
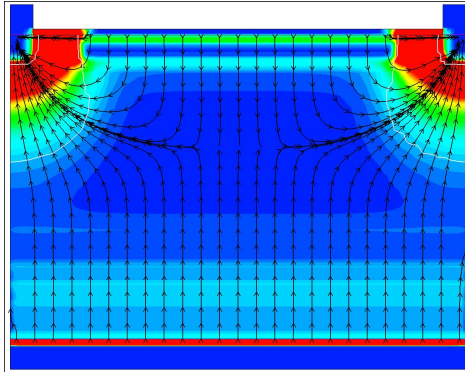


Allpix<sup>2</sup>: Monte Carlo Simulations  
for Semiconductor Detectors

<https://doi.org/10.1016/j.nima.2018.06.020>

- ★ Model semiconductor devices by means of finite element analysis
- ★ Electric Fields: accurate and realistic

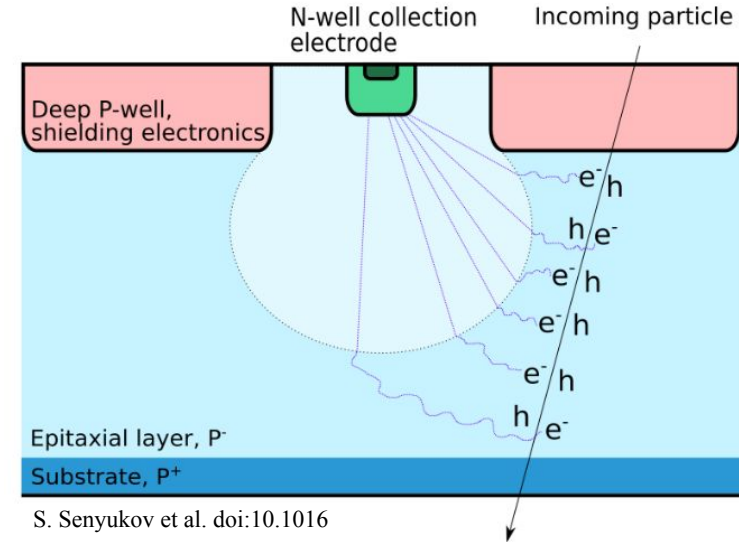
- ★ Simulate full response of semiconductor detector
- ★ Particle Events: fast and high statistics



# Layouts & Assumptions

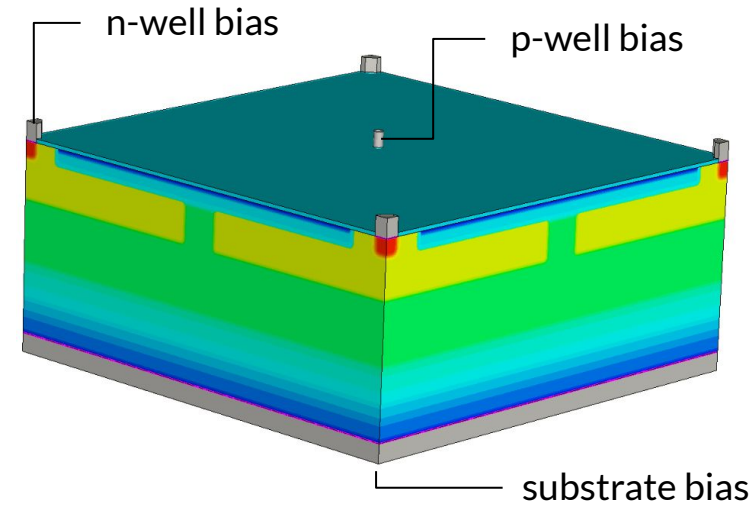
# General Layout & Assumptions

- ★ High-resistivity p-doped **epitaxial layer** grown on electronics-grade p-doped silicon **substrate**
- ★ Approximate public doping concentrations:
  - Substrate:  $10^{19} \text{ cm}^{-3}$
  - Epitaxial layer:  $3 \cdot 10^{13} \text{ cm}^{-3}$
  - Doping wells:  $10^{15}$  to  $10^{19} \text{ cm}^{-3}$
- ★ Doping wells simulated without internal structure and as flat profiles:
  - Small **collection n-well** in the centre of the pixel
  - **P-well** hosts and shields in-pixel CMOS electronics

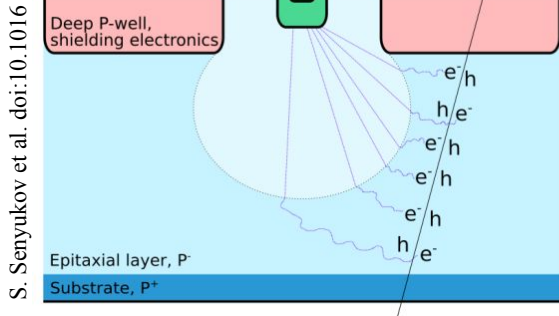


# Geometry & Layouts

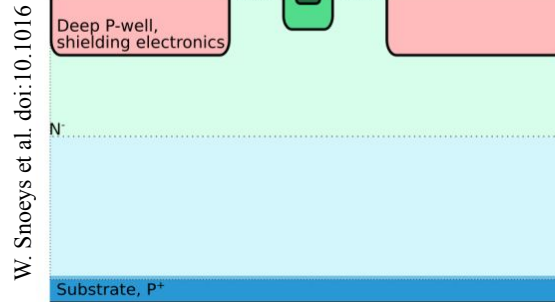
- ★ 3D geometry with collection wells in corners
- ★ Ohmic contacts simulated to provide bias voltages (highly-doped region)
- ★ Substrate is simulated only in Allpix<sup>2</sup>, not in TCAD
- ★ Rectangular and hexagonal pixel geometries (see [talk by H. Wennl6f](#))
- ★ Layouts with modifications to improve electric field



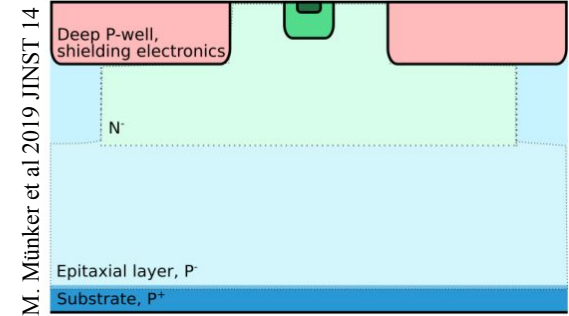
### Standard Layout



### N-Blanket Layout



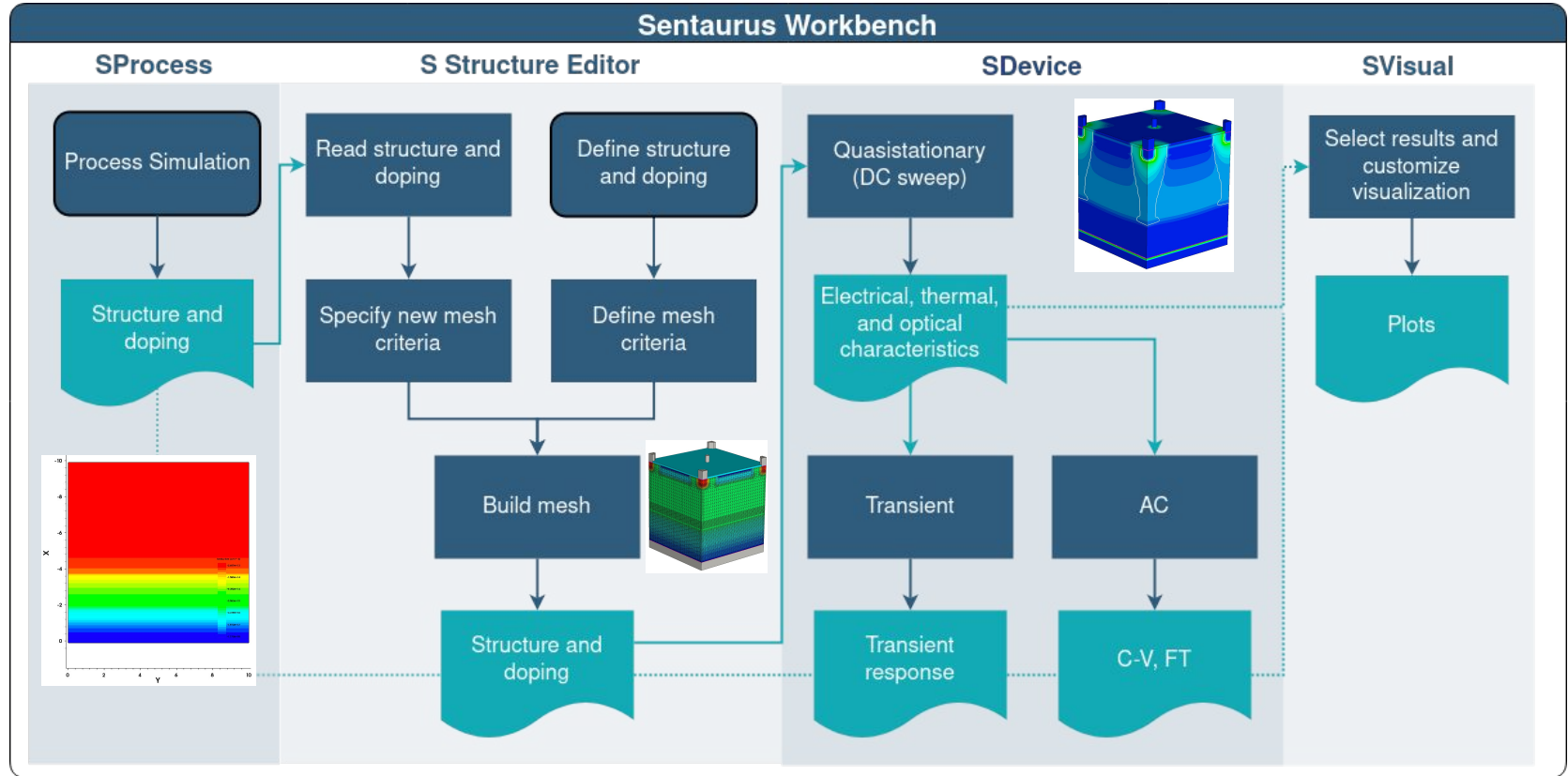
### N-Gap Layout





# Finite Element Simulations with TCAD

# TCAD Simulation Workflow Example



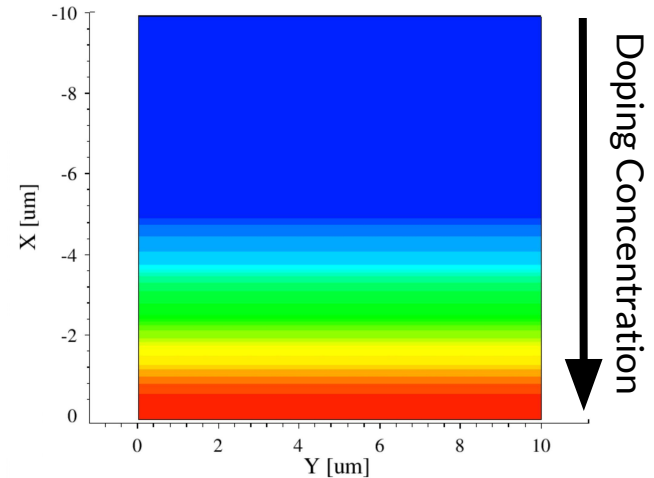
# TCAD Simulations

- ★ Scans over different parameters: well doping concentrations, mask geometries and operational voltage
- ★ Observe behavior of electric field, lateral electric field and depleted volume
- ★ Select parameters that reproduce expected physical behaviour

## TCAD - Process Simulations

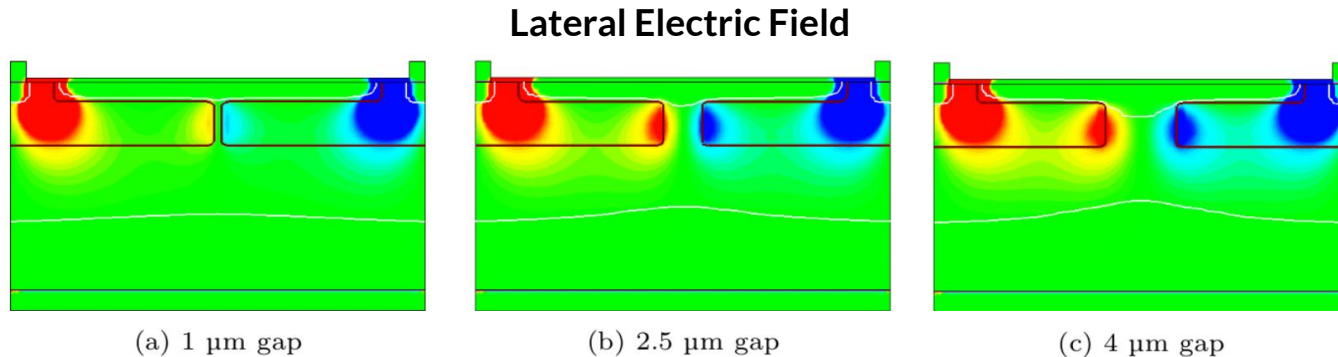
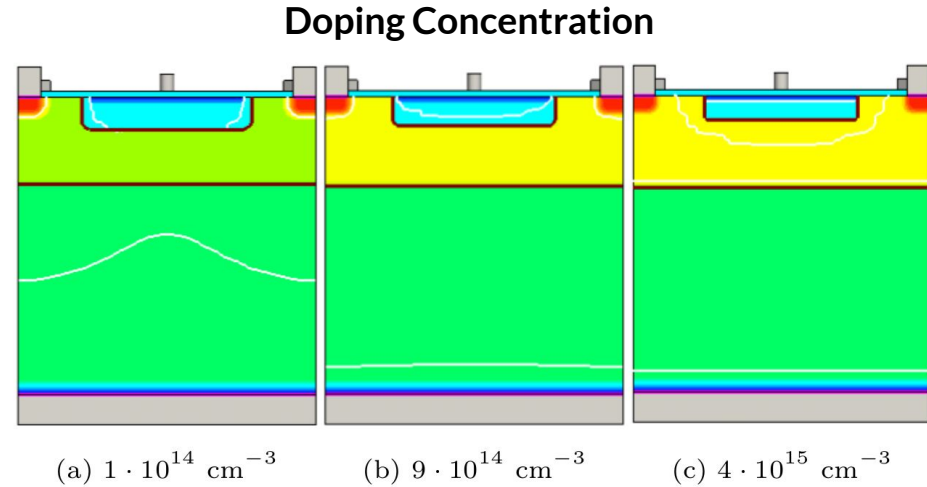
Effects from production process temperatures

- ★ Diffusion between different doping regions
- ★ Continuous interface between epitaxial layer and substrate



# TCAD - Quasistationary Simulations

- ★ N-blanket doping concentration scan
  - Impact on depleted volume (white line)
- ★ N-gap size scan
  - Impact on lateral electric field (red and blue regions)

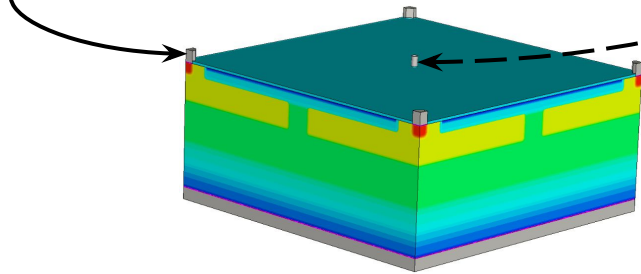


# TCAD - Transient Simulations

Time-dependent induced signal by MIP

## ★ MIP incidence comparison

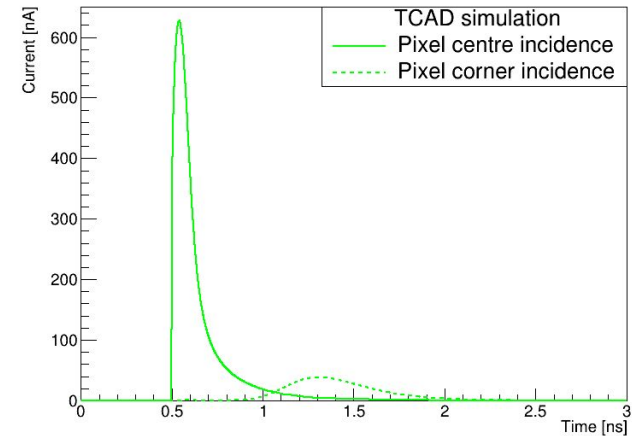
- Pixel corner “worst case scenario”
- Pixel centre “best case scenario”



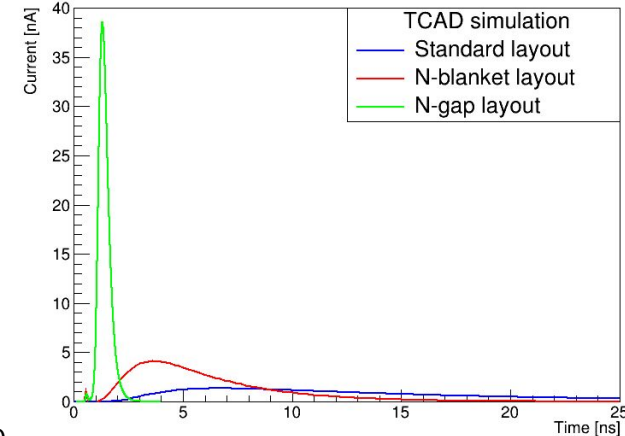
## ★ Layout comparison

- Improvements brought on by modifications

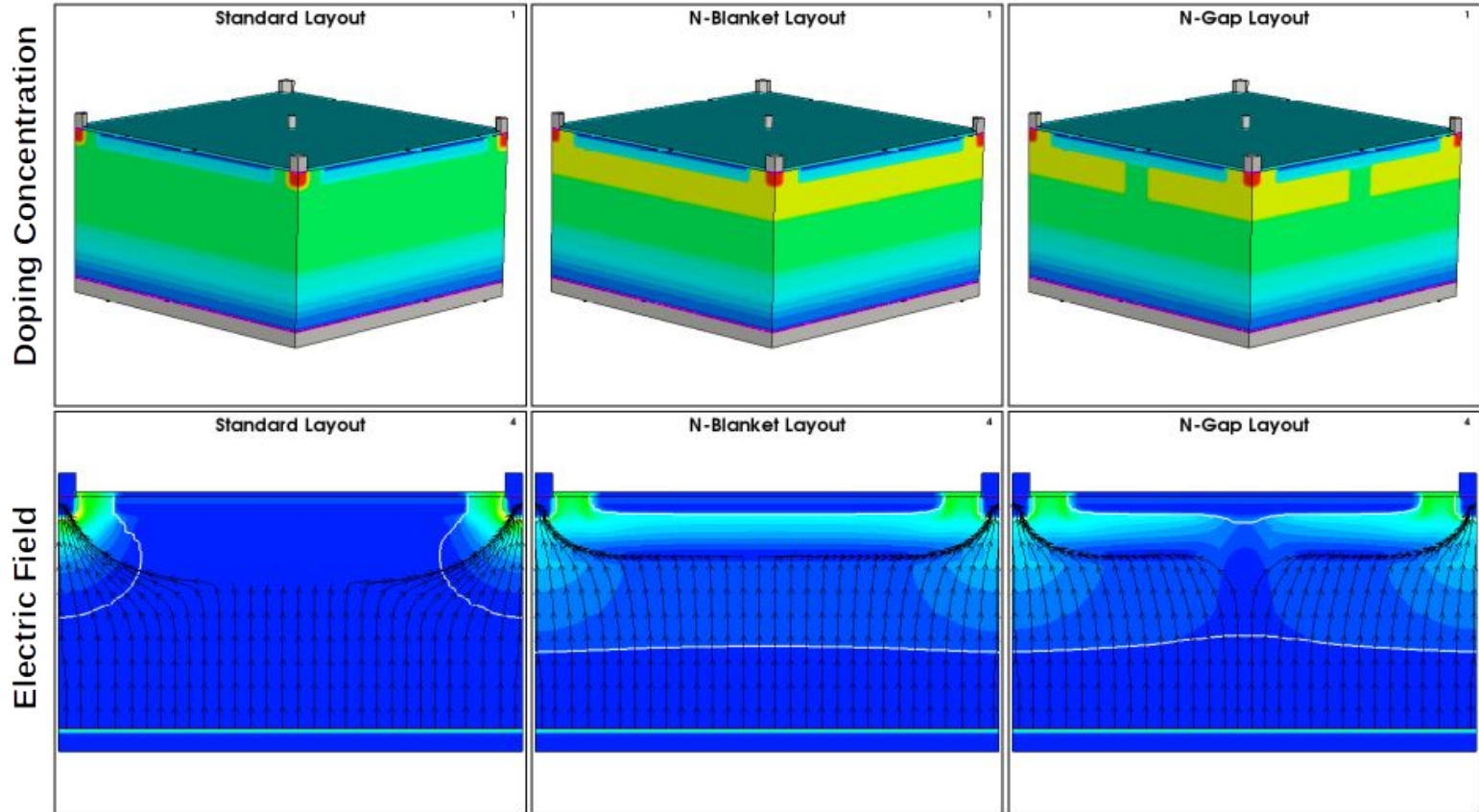
Square pixels,  $20 \times 20 \mu\text{m}^2$ , n-gap layout



Square pixels,  $20 \times 20 \mu\text{m}^2$ , corner incidence

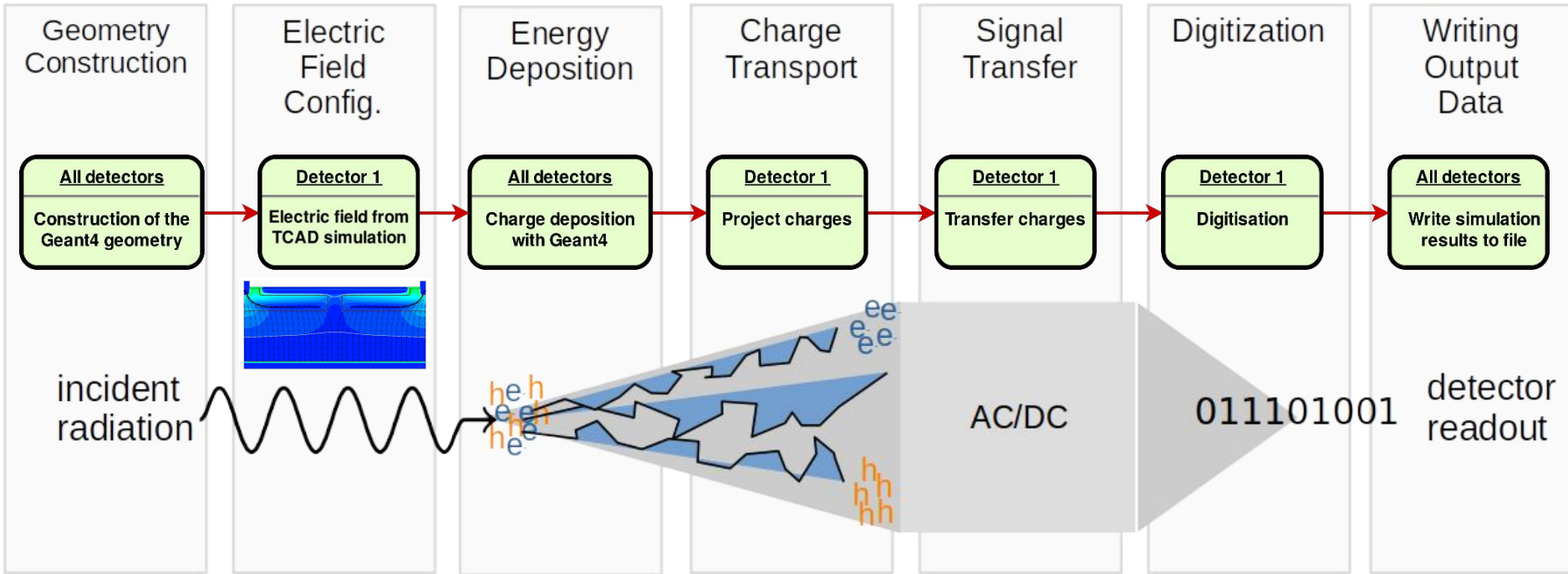


# TCAD Simulations - Final Result



# Monte Carlo Simulations with Allpix<sup>2</sup>

# Monte Carlo Simulation Workflow Example



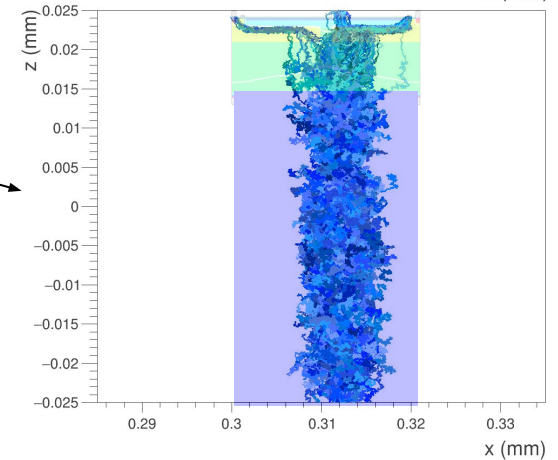
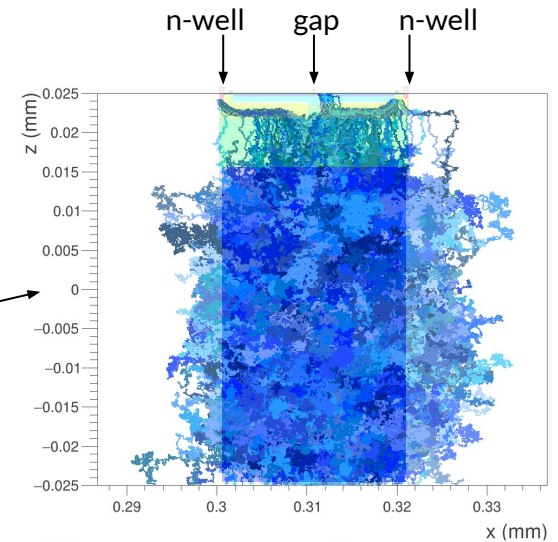


# Monte Carlo Simulations - Mobility

Take into account important details...

E.g.: Mobility Models

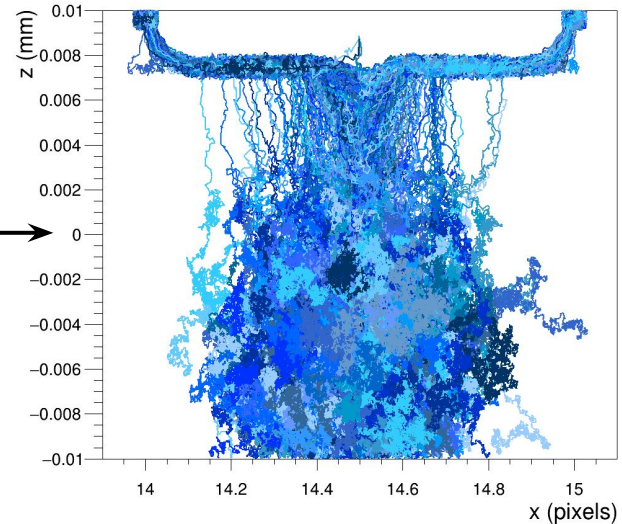
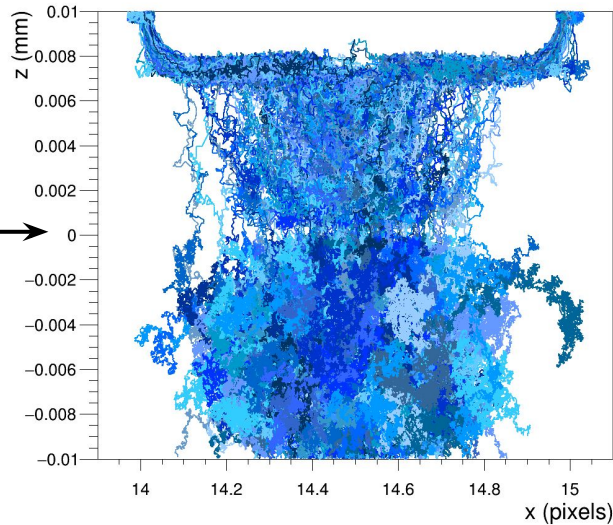
- ★ Jacoboni-Canali (doping-independent)
  - Sufficient for low doping concentration
  - For high doping concentration (substrate) diffusion is unphysically large
- ★ Masetti-Canali (doping dependent)
  - Fit for high doping concentration



# Monte Carlo Simulations - Diffusion

Comparing effect of electric field between substrate and epitaxial layer

- ★ Without dopant diffusion: significant electric field in interface region
  - Unphysical
- ★ With dopant diffusion: smooth transition region



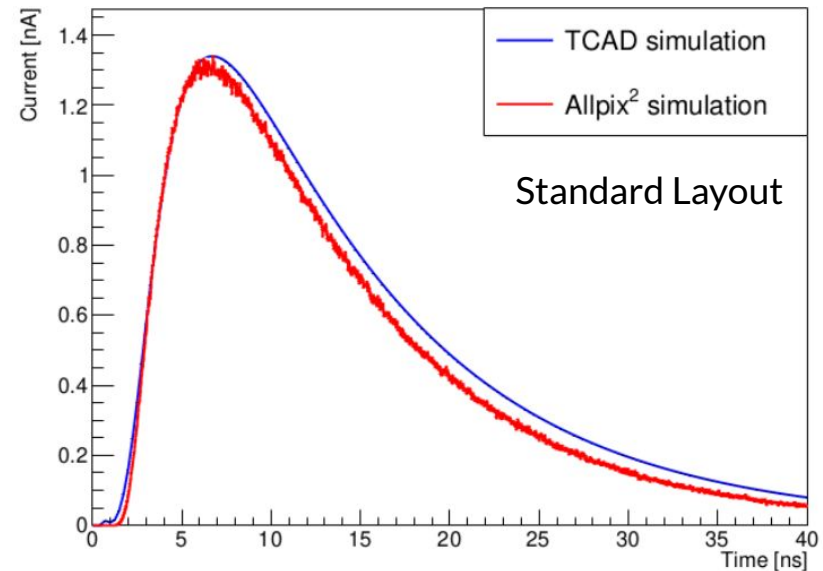
Electrostatic potentials from TCAD can be used to generate weighting potentials

→ Perform transient simulations with Allpix<sup>2</sup>

- ★ Lower computational cost
- ★ Reproduce many events
- ★ Allows use of Geant4 energy deposition (see next slide)

Comparison Allpix<sup>2</sup> vs. TCAD:

- ★ Same settings for charge carrier creation and mobility
- ★ Results in general agreement

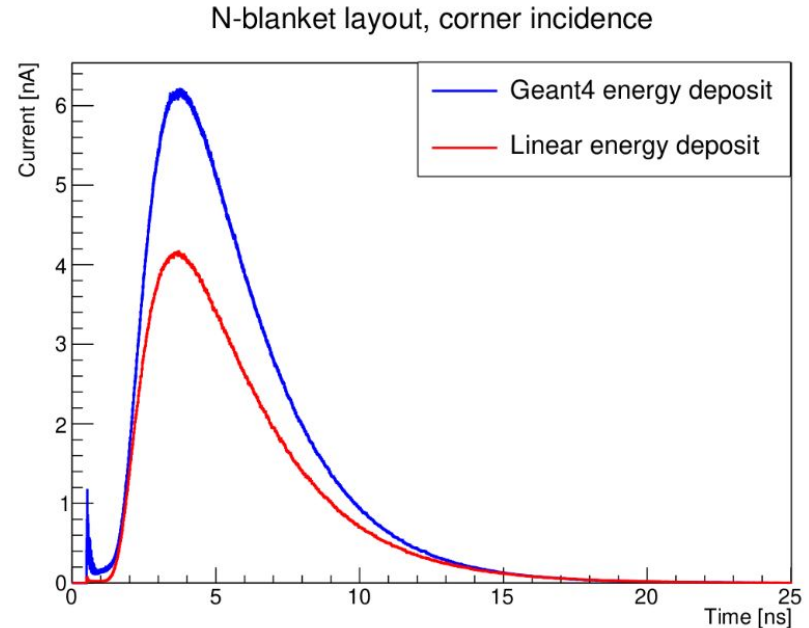


# Monte Carlo Simulations - Energy Deposition

Transient simulations comparing:

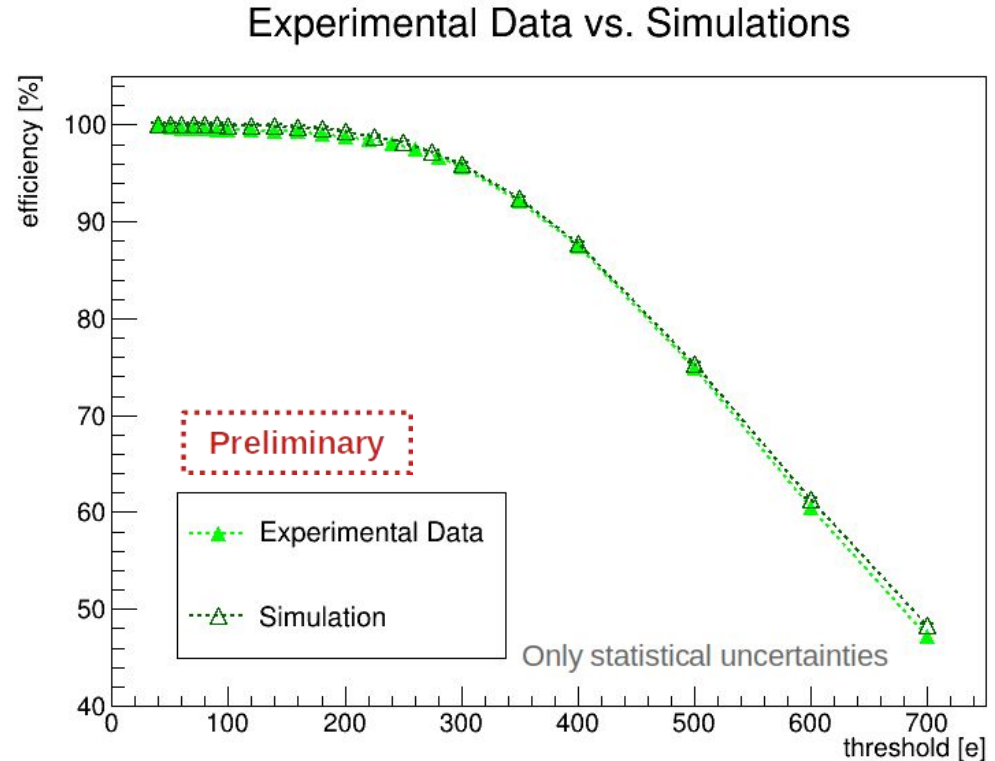
- ★ Linear energy deposition (TCAD)
  - Generates 63 electron-hole pairs per  $\mu\text{m}$   
→ most probable value
- ★ Geant4 (Allpix<sup>2</sup>)
  - Includes stochastic effects → takes into account all values from energy deposition distribution

Each signal is the average of 10 000 events, incident in the pixel corner



# Simulation vs. Experimental Data

- ★ First comparison with test-beam data
- ★ Analog Pixel Test Structure (APTS - [W. Deng et al.](#))
  - N-gap layout
  - 4x4 pixel matrix
  - 25  $\mu\text{m}$  pitch
  - -4.8 V bias voltage
- ★ Similar trend in experimental data and simulations
- ★ More results presented at [BTTB11](#)



# Summary & Conclusions

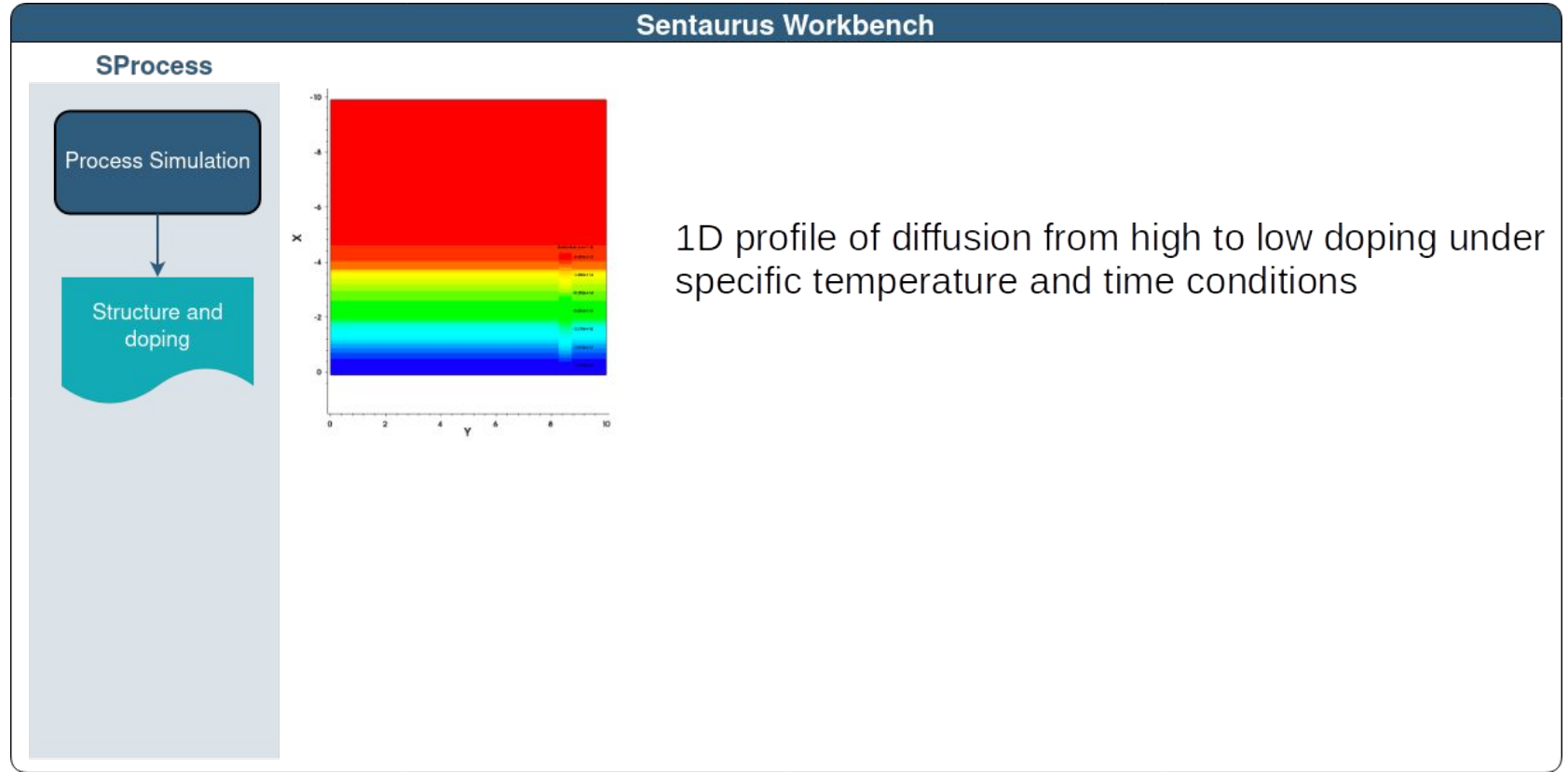
- ★ Description of simulation procedure for MAPS → **generic toolbox** for performing similar studies
- ★ Starting from generic doping profiles and semiconductor principles → realistic doping and electric field maps are produced with TCAD
- ★ Parameters are varied to find sensible values
- ★ Maps are imported into Allpix<sup>2</sup> → high-statistics Monte Carlo simulations are performed
- ★ Sensor performance observables are extracted and compared to data

## Outlook

- ★ Validation with experimental data
- ★ Add uncertainties on simulation results

# Back-up

# TCAD Simulation Workflow Example



Legend:

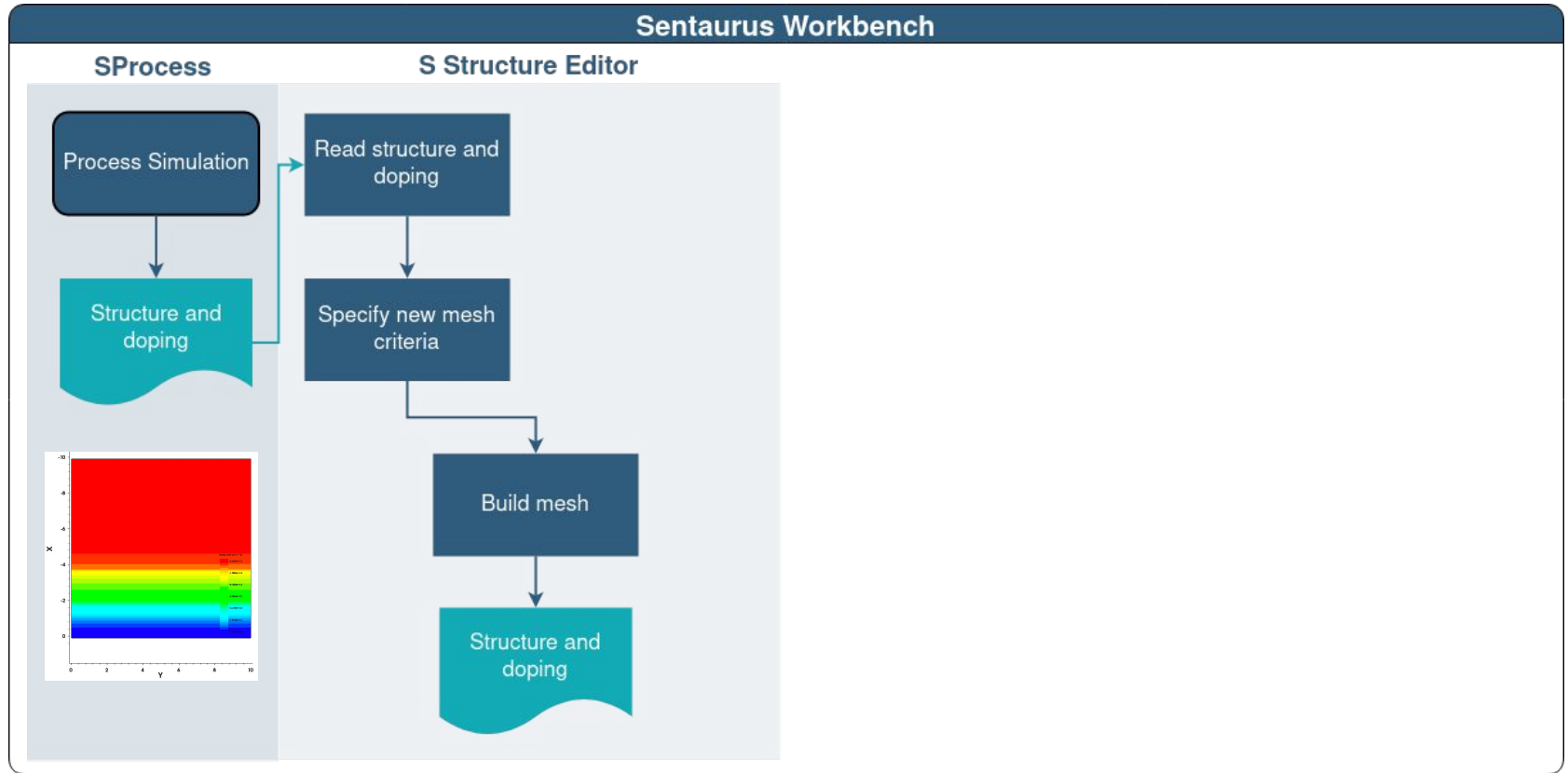
Start

Step

Result



# TCAD Simulation Workflow Example



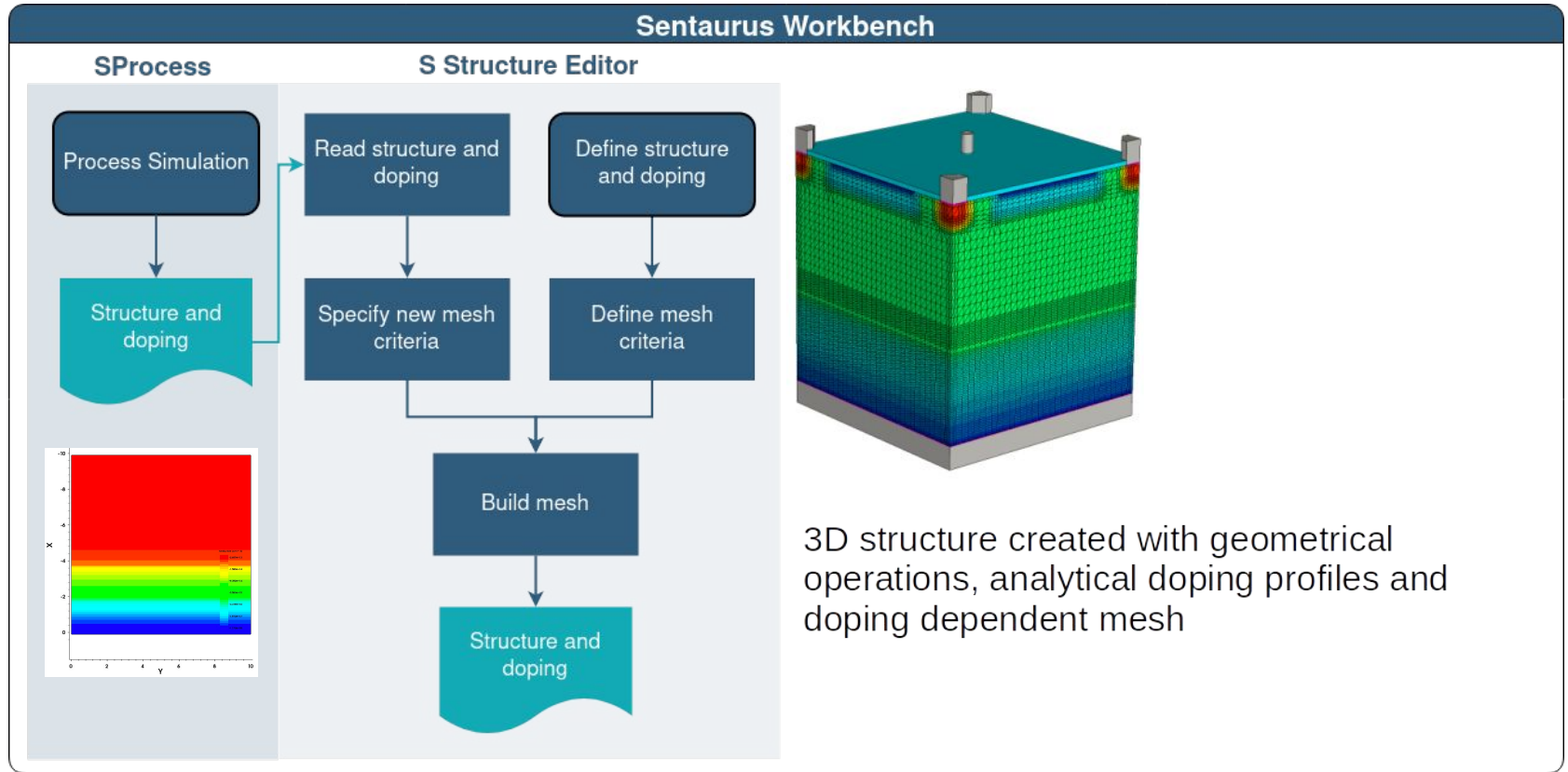
Legend:

Start

Step

Result

# TCAD Simulation Workflow Example



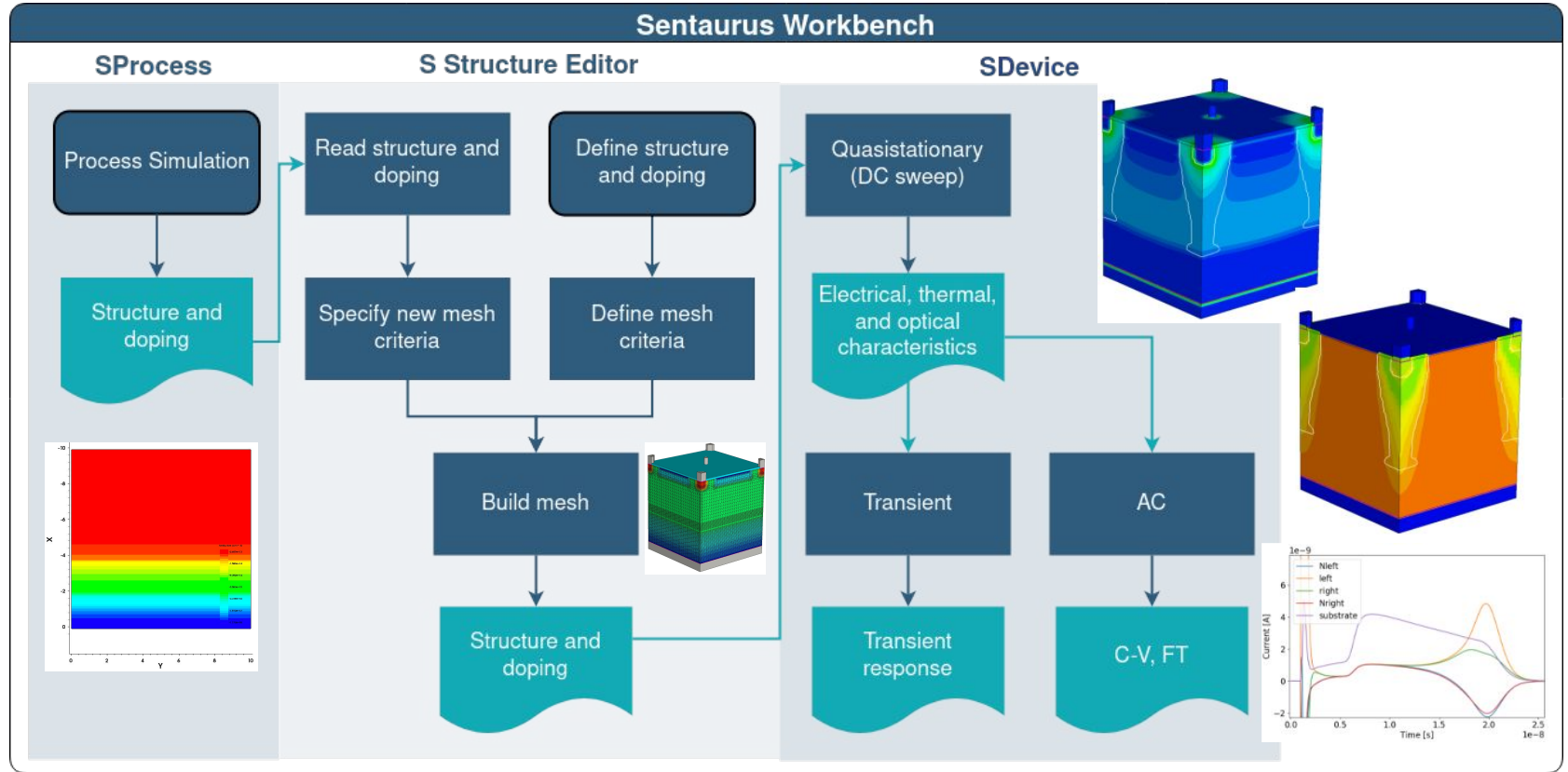
Legend:

Start

Step

Result

# TCAD Simulation Workflow Example



Legend:

Start

Step

Result